

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property
Organization
International Bureau

(43) International Publication Date
04 May 2023 (04.05.2023)



(10) International Publication Number
WO 2023/075968 A1

(51) International Patent Classification:

H01J 37/20 (2006.01) H01J 37/317 (2006.01)
H01L 21/683 (2006.01)

(21) International Application Number:

PCT/US2022/044859

(22) International Filing Date:

27 September 2022 (27.09.2022)

(25) Filing Language:

English

(26) Publication Language:

English

(30) Priority Data:

17/510,991 26 October 2021 (26.10.2021) US

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(81) Designated States (*unless otherwise indicated, for every
kind of national protection available*): AE, AG, AL, AM,
AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ,
CA, CH, CL, CN, CO, CR, CU, CV, CZ, DE, DJ, DK, DM,
DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT,
HN, HR, HU, ID, IL, IN, IQ, IR, IS, IT, JM, JO, JP, KE,
KG, KH, KN, KP, KR, KW, KZ, LA, LC, LK, LR, LS, LU,
LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA,
NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO,
RS, RU, RW, SA, SC, SD, SE, SG, SK, SL, ST, SV, SY, TH,
TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, WS,
ZA, ZM, ZW.

(54) Title: CHUCK FOR PROCESSING SEMICONDUCTOR WORKPIECES AT HIGH TEMPERATURES

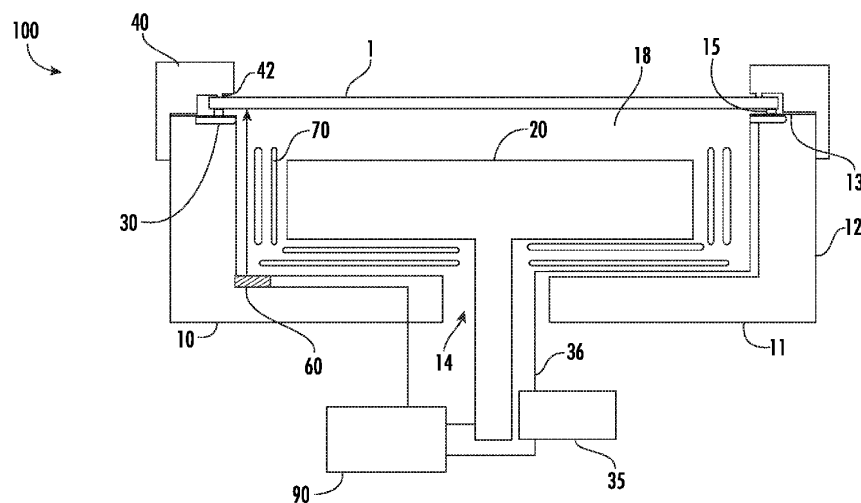


FIG. 1

(57) Abstract: A chuck for heating and clamping a workpiece, such as a semiconductor workpiece, is disclosed. The chuck is configured to allow the workpiece to be heated to temperatures in excess of 600C. Further, while the workpiece is heating, the components that make up the chuck may be maintained at a much lower temperature, such as room temperature. The chuck includes a housing, formed as a hollow cylinder with sidewalls and an open end. Electrodes are disposed at the top surface of the sidewalls to clamp the workpiece. A heat source is disposed in the cavity and emits radiated heat toward the workpiece. A clamp ring may be used to secure the workpiece. In some embodiments, a thermal sensor is used to monitor the temperature of the workpiece.

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WO 2023/075968 A1

(84) Designated States (*unless otherwise indicated, for every kind of regional protection available*): ARIPO (BW, GH, GM, KE, LR, LS, MW, MZ, NA, RW, SD, SL, ST, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, KM, ML, MR, NE, SN, TD, TG).

Published:

— with international search report (Art. 21(3))